

TH 211-3 Non Silicone Gap Filler

Description

TH 211-3 is a yellowish white, highly filled non silicone system suitable thermal dissipation of electronic devices. It has stable pot life and long shelf life even at room temperature of 25°C.

Applications

1. Heat dissipation from electronic components.

Guidelines for Use

1. Wear rubber gloves when handling the product.
2. Pick up some of the product from the container using hand.
3. Place the product in required electronic part and circuit by hand.
4. Not require heating and curing.
5. The product can be applied and removed easily (care must be taken during installation to avoid tearing).

Properties

Property	Test Method	Unit	Typical Value
Appearance	PEN 10	-	Yellowish white
Tackiness	-	-	One Side Sticky
Viscosity, Brookfield Cap 2000+, 25°C	PEN 44	cP	Pad
Operating Temperature	PEN 92	°C	-40 to 125
Decompose Temperature	PEN 92	°C	230
Thermal Conductivity	ASTM D5470	W/mK	1.4
Thermal Resistance	ISO/DIS 22007	m ² K/W	0.0038/2mm 0.0077/4mm
Density	PEN 14	g/cm ³	1.5

Storage

Store this silicone thermal pad in air tight container, cool, dark place (temperature range from 20°C to 30°C) to prolong shelf life. Prevent moisture condition.

Packaging

- Sheet form
- Will provide customized dimension if required

Environment, Health & Safety

This product is RoHS compliant. It does not contain any known carcinogenic, mutagenic or teratogenic components.

Contact Information

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